

**In the Claims:**

Please cancel claims 51-53 and 75-77. Please cancel claims 47, 54, 56, 57, 78, 80, and 81. Please amend claims 1 and 41. The claims are as follows:

1. (Currently amended) An encapsulant composition comprising:

a resin material selected from the group consisting of epoxy and cyanate ester resins;  
a flexibilizing agent comprising 2 percent to about 5 percent by weight of said composition from about 1.0% by weight to about 5% by weight of the composition of a flexibilizing agent comprising a flexibilizer containing functional groups capable of reaction with the epoxy or cyanate ester resin during thermally induced curing, and a thermoplastic other than the flexibilizer, wherein the thermoplastic is separated from the cured epoxy or cyanate ester resin; and

a filler material comprising substantially spherical or spheroidal particles, each particle having a diameter of less than about 41 microns,

wherein the composition has a higher fracture toughness, a lower viscosity, and increased thermal shock resistance at a temperature excursion below -40 °C, or combinations thereof than the composition would have if the flexibilizing agent were not present in the composition.

2-13. (Canceled)

14. (Previously presented) The composition of claim 1, wherein a portion of each of said spherical or spheroidal particles includes a layer of coupling agent positioned thereon, and

09/778,996

2

wherein the coupling agent comprises about 0.25% by weight of the filler material.

15-17. (Canceled)

18. (Previously presented) An electronic package comprising:

a substrate having an upper surface;

a semiconductor chip mounted on a portion of said upper surface of said substrate and electrically coupled to said substrate, said semiconductor chip having a bottom surface and at least one edge surface being substantially perpendicular to said bottom surface; and

a material positioned on at least said portion of said upper surface of said substrate and against at least a portion of said at least one edge surface of said semiconductor chip, said material being the encapsulant composition of claim 1.

19-40. (Canceled)

41. (Currently amended) A method of making an encapsulant composition, the method comprising the steps of:

providing a first quantity of resin material selected from the group consisting of epoxy and cyanate ester resins;

adding to said first quantity of resin material a second quantity of flexibilizing agent by homogenizing said flexibilizing agent in said first quantity of resin material by reacting said resin material and said flexibilizing agent together at a temperature of greater than about 100 degrees

09/778,996

3

Celsius, from about 1.0% by weight to about 5% by weight of the composition of said  
flexibilizing agent comprising a flexibilizer containing functional groups capable of reaction with  
the epoxy or cyanate ester resin during thermally induced curing, and a thermoplastic other than  
the flexibilizer, wherein the thermoplastic is separated from the cured epoxy or cyanate ester  
resin;

adding to said first quantity of resin material a third quantity of filler material comprising substantially spherical or spheroidal particles, each particle having a diameter of less than about 41 microns; and

blending said resin material, wherein after said blending said flexibilizing agent comprises 2 percent to about 5 percent by weight of said composition,

wherein immediately after the steps of adding the flexibilizing agent and adding the filler material have been performed the composition is uncured and the composition is stable for a time period at least 12 hours,

wherein the composition has a higher fracture toughness, a lower viscosity, and increased thermal shock resistance at a temperature excursion below -40 °C, or combinations thereof than the composition would have if the flexibilizing agent were not present in the composition.

42. (Canceled)

43. (Previously presented) The method of claim 41, wherein said step of blending is performed under vacuum.

09/778,996

4

44. (Previously presented) The method of claim 43, wherein said step of blending is performed under vacuum at a pressure of about 5 millimeters of mercury.

45. (Canceled)

46. (Previously presented) The method of claim 41, wherein a portion of each of said spherical or spheroidal particles includes a layer of coupling agent positioned thereon, and wherein the coupling agent comprises about 0.25% by weight of the filler material.

47. (Withdrawn) The method of claim 41, wherein the method further comprises the steps of:

after the steps of adding the flexibilizing agent and adding the filler material, applying the composition to a gap between a substrate and a semiconductor chip, wherein the semiconductor chip is assembled to the substrate by Controlled Collapse Chip Connection (C4) interconnections, wherein the composition completely covers the C4 interconnections, wherein said applying the composition to the gap comprises dispensing the composition through nozzles under pressure between about 15 pounds per square inch and about 90 pounds per square inch at a temperatures between about 25 degrees °C and about 45 degrees °C to a surface of the substrate on which the semiconductor is assembled and to at least a portion of edges of a device that comprises the semiconductor chip so as to form a fillet;

after the step of applying the composition to the gap, pregelling the composition by heating the composition for a period of time between about 15 and about 60 minutes at a temperature between about 75 °C and about 100 °C; and

09/778,996

5

after the pregelling step, substantially curing the composition by heating the composition to a temperature between about 130 °C and about 180 °C for a period of time between about 2 and about 4 hours.

47-57. (Canceled)

58. (Previously presented) The composition of claim 1, wherein the resin material consists of epoxy resins, wherein the composition further comprises a surfactant comprising that facilitates mixing the filler with the epoxy resins, wherein the surfactant comprises non-ionic type surface active agents, and wherein the surfactant comprises between about 0.5% and about 3% by weight of the composition.

59. (Previously presented) The composition of claim 1, wherein the filler material has a negative coefficient of thermal expansion.

60. (Previously presented) The composition of claim 1, wherein the composition further comprises an organic dye comprising less than about 0.2% by weight of the composition.

61. (Previously presented) The composition of claim 1, wherein the composition further comprises non-reactive organic solvents comprising less than about 0.2% by weight of the composition or the composition is completely free of non-reactive organic solvents.

62. (Previously presented) The composition of claim 1, wherein the composition is cured and has a coefficient of thermal expansion between about 25 and about 40 ppm/° C, a glass transition temperature between about 140° and about 190° C, and a Shore D hardness greater than about 90.

63-81. (Canceled)

82. (Previously presented) The method of claim 41, wherein the resin material consists of epoxy resins, wherein the composition further comprises a surfactant comprising that facilitates mixing the filler with the epoxy resins, wherein the surfactant comprises non-ionic type surface active agents, and wherein the surfactant comprises between about 0.5% and about 3% by weight of the composition.

83. (Previously presented) The method of claim 41, wherein the filler material has a negative coefficient of thermal expansion.

84. (Previously presented) The method of claim 41, wherein the composition further comprises an organic dye comprising less than about 0.2% by weight of the composition.

85. (Previously presented) The method of claim 41, wherein the composition further comprises non-reactive organic solvents comprising less than about 0.2% by weight of the composition or the composition is completely free of non-reactive organic solvents.

09/778,996

7

86. (Previously presented) The method of claim 41, wherein after the substantially curing step, the composition has a coefficient of thermal expansion between about 25 and about 40 ppm/<sup>o</sup> C, a glass transition temperature between about 140<sup>o</sup> and about 190<sup>o</sup> C, and a Shore D hardness greater than about 90.

87. (Previously presented) The composition of claim 1, wherein the resin material consists of epoxy resins, and wherein the epoxy resins comprise 3',4'-epoxycyclohexylmethyl 3,4-epoxycyclohexanecarboxylate.

88. (Previously presented) The composition of claim 54, wherein the thermoplastic comprises a poly(arylene) ether, and wherein the first flexibilizer comprises bis(2,3-epoxy-2-methylpropyl)ether.

89. (Previously presented) The composition of claim 1, wherein the filler material comprises zirconium tungstate.

90. (Currently amended) The composition of claim 14, wherein the coupling agent comprises b-(3,4-epoxycyclohexyl) ethyltrimethoxy silane.

91. (Previously presented) The composition of claim 58, wherein the surfactant comprises polyethylene glycol-p-tert-octylphenyl ether .

92. (Previously presented) The composition of claim 60, wherein the organic dye comprises nigrosine.

93. (Previously presented) The method of claim 41, wherein the resin material consists of epoxy resins, and wherein the epoxy resins comprise 3',4'-epoxycyclohexylmethyl 3,4-epoxycyclohexanecarboxylate.

94. (Previously presented) The method of claim 78, wherein the thermoplastic comprises a poly(arylene) ether, and wherein the first flexibilizer comprises bis(2,3-epoxy-2-methylpropyl)ether.

95. (Previously presented) The method of claim 41, wherein the filler material comprises zirconium tungstate.

96. (Previously presented) The method of claim 46, wherein the coupling agent comprises b-(3,4-epoxycyclohexyl) ethyltrimethoxy silane.

97. (Previously presented) The method of claim 82, wherein the surfactant comprises polyethylene glycol-p-tert-octylphenyl ether.

98. (Previously presented) The method of claim 84, wherein the organic dye comprises nigrosine.